

L	Hits	Search Text	DB	Time stamp
Number				
1	461	137/112.ccls.	USPAT;	2004/04/19
			US-PGPUB	14:05
2	265	137/113.ccls.	USPAT;	2004/04/19
			US-PGPUB	14:05
3	636	222/148.ccls.	USPAT;	2004/04/19
			US-PGPUB	14:05
4	184	222/152.ccls.	USPAT;	2004/04/19
i			US-PGPUB	14:05
-	0	chmeical adj delivery same (semiconductor adj	USPAT;	2004/04/19
		fabrication and process adj tool)	US-PGPUB	11:21
	5	chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
		fabrication and process adj tool)	US-PGPUB	11:21
_	1	6264064.URPN.	USPAT	2004/04/19
	•	025405 1.5Ki Ki		11:26
_	1	6264064.URPN.	USPAT	2004/04/19
	1	0204004.0RFN.	03171	11:26
	14	("3100885"   "4053085"   "4440319"	USPAT	2004/04/19
-	14	( 3100665   4053065   4440319     "4580448"   "4770038"   "4949878"	USPAT	11:26
		, , , , , , , , , , , , , , , , , , , ,		11.20
	!	"5199603"   "5303585"   "5562132"		
		"5663503"   "6077356"   "6202484"		
		"6264064"   "6397656"   "2002/0108670").PN.		0004/04/40
-	14	("3100885"   "4053085"   "4440319"	USPAT	2004/04/19
		"4580448"   "4770038"   "4949878"		11:26
ļ		"5199603"   "5303585"   "5562132"		
		"5663503"   "6077356"   "6202484"		
1		"6264064"   "6397656"   "2002/0108670").PN.		
_	1	6264064.URPN.	USPAT	2004/04/19
				11:27
_	1	6264064.URPN.	USPAT	2004/04/19
	_			11:27
_	2	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
	-	fabrication and process adj tool)) and	US-PGPUB	11:29
ŀ		141/302.ccls.		
	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
-	0	fabrication and process adj tool)) and	US-PGPUB	11:29
			05 ( 0, 05	11.23
		141/1.ccls. (chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
-	1		US-PGPUB	11:30
		fabrication and process adj tool)) and	03-70700	11.50
		141/47.ccls.	LICDAT.	2004/04/19
-	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
		fabrication and process adj tool)) and	US-PGPUB	11:30
		141/49.ccls.		
-	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
1		fabrication and process adj tool)) and	US-PGPUB	11:30
		141/104.ccls.		
-	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
		fabrication and process adj tool)) and	US-PGPUB	11:30
1	[	134/16C.ccls.		
-	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
		fabrication and process adj tool)) and	US-PGPUB	11:42
		134/166C.ccls.		
_	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
1		fabrication and process adj tool)) and	US-PGPUB	11:31
		134/1.3.ccls.		
L		137/1.3.003.	L	

-	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
		fabrication and process adj tool)) and	US-PGPUB	11:41
		134/1.2.ccls.		
_	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
	_	fabrication and process adj tool)) and	US-PGPUB	11:41
		134/22.14.ccls.	00 / 0. 01	
	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
-	١		US-PGPUB	11:41
		fabrication and process adj tool)) and	03-49400	11.71
		134/22.19.ccls.	LICOAT	2004/04/40
-	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
		fabrication and process adj tool)) and	US-PGPUB	11:41
		134/94.1.ccls.		
-	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
		fabrication and process adj tool)) and	US-PGPUB	11:41
		134/95.1.ccls.		
_	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
	_	fabrication and process adj tool)) and	US-PGPUB	11:41
		134/98.1.ccls.		·
<u>-</u>	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
-	J 3	fabrication and process adj tool)) and	US-PGPUB	11:42
		134/99.2.ccls.	30,3,00	
	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
-	U		US-PGPUB	11:42
		fabrication and process adj tool)) and	03-4940	11.42
	_	134/102.2.ccls.	LICDAT	2004/04/10
-	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
		fabrication and process adj tool)) and	US-PGPUB	11:42
		134/171.ccls.		
-	0	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
	i	fabrication and process adj tool)) and	US-PGPUB	11:43
		137/15.04.ccls.		
_	o	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
	_	fabrication and process adj tool)) and	US-PGPUB	11:43
		137/15.05.ccls.		
1_	1	(chemical adj delivery same (semiconductor adj	USPAT;	2004/04/19
	_	fabrication and process adj tool)) and	US-PGPUB	11:43
		137/209.ccls.		
	0	1	USPAT;	2004/04/19
-	"	fabrication and process adj tool)) and	US-PGPUB	11:44
		137/240.ccls.	USPAT;	2004/04/19
-	0	, , , , , , , , , , , , , , , , , , , ,	US-PGPUB	11:44
		fabrication and process adj tool)) and	03-20208	11.44
		137/883.ccls.	LICEAT	2004/04/10
-	0		USPAT;	2004/04/19
	1	fabrication and process adj tool)) and	US-PGPUB	11:44
		137/885.ccls.		
-	498352	"6199599" B1	USPAT;	2004/04/19
			US-PGPUB	11:47
-	3	"6199599"	USPAT;	2004/04/19
			US-PGPUB	11:47
-	1	6457494.URPN.	USPAT	2004/04/19
	]			11:47
_	1	6457494.URPN.	USPAT	2004/04/19
	1			11:47
	1		<del></del>	L

-	43	("2160062"   "2536273"   "2777914"	USPAT	2004/04/19
		"3034543"   "3081905"   "3419695"		11:48
		"3646293"   "3653549"   "3731805"		
		"3930591"   "4056979"   "4064755"		
		"4134514"   "4298037"   "4425949"		
		"4436674"   "4576552"   "4676404"		
		"4730491"   "4859375"   "4976146"		
		"4979545"   "4979643"   "5038840"		
		"5041267"   "5069244"   "5079950"		
		"5090212"   "5103673"   "5137063"		
		"5148945"   "5279338"   "5285812"		
		"5329963"   "5465766"   "5479959"		
		"5551309"   "5562132"   "5590695"		
		"5607002"   "5628342"   "5711354"		
		"5878793").PN.		
_	43	("2160062"   "2536273"   "2777914"	USPAT	2004/04/19
		"3034543"   "3081905"   "3419695"		11:48
:		"3646293"   "3653549"   "3731805"		
		"3930591"   "4056979"   "4064755"		
		"4134514"   "4298037"   "4425949"		
		"4436674"   "4576552"   "4676404"		
		"4730491"   "4859375"   "4976146"		
		"4979545"   "4979643"   "5038840"		
		"5041267"   "5069244"   "5079950"		
		"5090212"   "5103673"   "5137063"		
		"5148945"   "5279338"   "5285812"		·
I	1	#5000000# L #5465766# L #5470050# L	I	

"5329963" | "5465766" | "5479959" | "5551309" | "5562132" | "5590695" | "5607002" | "5628342" | "5711354" |

"5878793").PN.